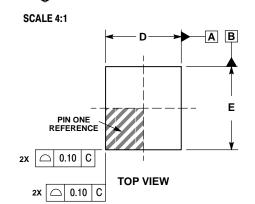
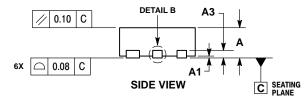
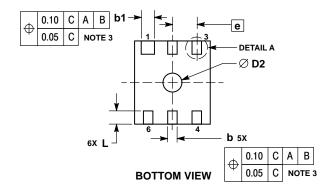
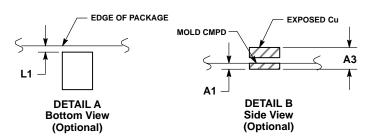


DATE 06 FEB 2006









- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED
- DIMENSION O APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
 0.25 AND 0.30mm FROM TERMINAL
 COPLANARITY APPLIES TO THE EXPOSED
 PAD AS WELL AS THE TERMINALS.
- TERMINAL b MAY HAVE MOLD COMPOUND MATERIAL ALONG SIDE EDGE.
- DETAILS A AND B SHOW OPTIONAL VIEWS FOR END OF TERMINAL LEAD AT EDGE OF PACKAGE AND SIDE EDGE OF PACKAGE.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.80	0.90	1.00	
A1	0.00	0.03	0.05	
A3	0.20 REF			
b	0.20	0.25	0.30	
b1	0.30	0.35	0.40	
D	2.00 BSC			
D2	0.40	0.50	0.60	
E	2.20 BSC			
е	0.65 BSC			
L	0.30	0.35	0.40	
L1	0.00	0.05	0.10	

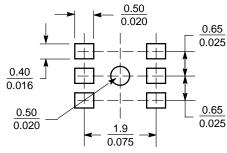
GENERIC MARKING DIAGRAM*



= Specific Device Code XX = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.

SOLDERING FOOTPRINT*



SCALE 10:1

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DFN6 2 X 2.2 X 0.9 X 0.65P		PAGE 1 OF 1	

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